

致力于成为全球一流的
小批量样板以及快板品牌制造商

Aiming To Become The 1st Class Prototype &
Quick Turn PCB Provider.



WEIYUANDA
INDUSTRIAL CO., LTD

東莞茂昌電子線路板有限公司



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Website: www.wyd-pcb.com

www.wyd-pcb.com

威震四海，
遠帆启航，
達不負望。



- 1.20年专业印刷线路板生产
- 2.单面板 - 24层研发板 / 快板 / 多品种小批量
- 3.刚性印刷线路板 / 铝基板 / 高频板 / 厚铜板 / 高精密线路板
- 4.ISO 9001 / ISO 14001 / ISO 13485 / IATF 16949
- 5.IPC 会员 / CIT 培训资格证
- 6.24位工程师 / 6 小时工程问客以及生产稿
- 7.报价 2 小时起

- 1.PCB Manufacture Experience 20 Years +
- 2.Single Sided to 24 Layers Prototype / Quick Turn / High Mix Low Volume
- 3.Rigid PCB / Aluminum PCB / High Frequency / Heavy Copper / HDIs
- 4.ISO 9001 / ISO 14001 / ISO 13485 / IATF 16949
- 5.IPC Member / CIT Certificated
- 6.Over 24 Engineers / 6 Hours TQ & Working Gerber
- 7.RFQs within 2 Hours



Management Team
管理团队

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ABOUT US

威远达实业有限公司（WYD）是一家总部坐落于香港，全资控股在中国广东省东莞市的生产基地-东莞茂昌电子线路板有限公司。

我们专注于PCB快板、研发 PCB 和多品种小批量生产，拥有刚性 FR-4 / 高频 / 铝基 PCB 生产的 UL 认证。

我们的工厂拥有 ISO 9001、ISO 14001、ISO 13485、IATF 16949 医疗和汽车等生产认证。

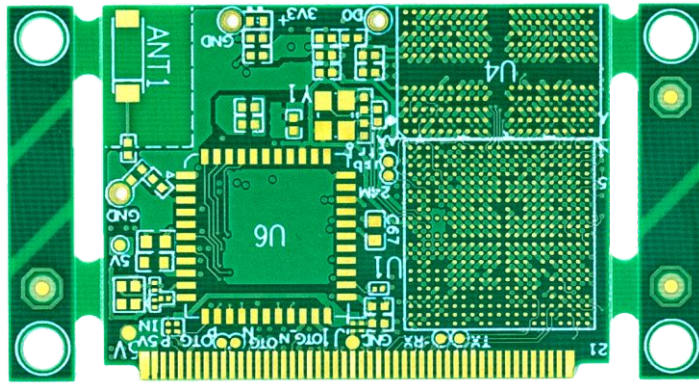
我们的专业生产团队，每天处理生产型号高达 170 余款。多层板占比高达百分之 65%。月产出达到 10,000 平方米。我们有 250 名经验丰富的生产人员，以及 10 名工艺工程师，10 名品质流程监控工程师。生产部人员平均经验为 5 年以上，员工稳定为公司的持续、健康发展提供了有力保障。为研发型和终端客户在最短的时间内提供所需的线路板及电子产品解决方案，帮助客户用最短时间推出具有竞争力的产品。

Weiyuanda Industrial Co., Ltd (WYD) is a Hong Kong based company with 100% holding of production site in China Dongguan -- Dongguan MaoChang Printed Circuit Board Limited, a professional PCB factory for Quick Turn PCB, Prototype PCB and High Mix Low Volume fabrication. With UL certification for Rigid FR-4 / High Frequency / Aluminum Based PCB production.

Our factory had been certificated with ISO 9001, ISO 14001, ISO 13485, IATF 16949 for Medical and Automotive application.

170 part numbers for quick turn production as daily output. and multilayer pcbs takes part over 65% proportion.

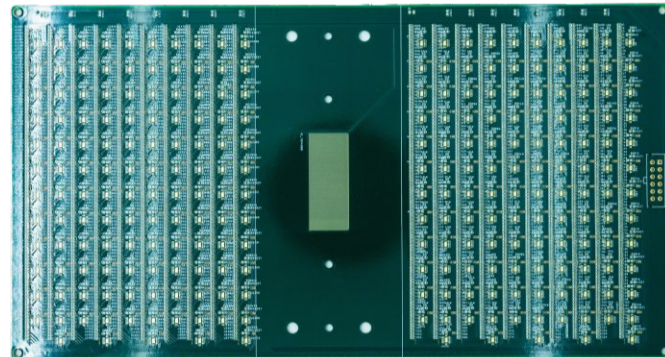
Monthly production capacity over 10,000sqm, We have more than 250 employees and 10 experienced R&D team, 10 IPQC Staff. 5 years PCB related experience are requested from all out employees for fulfilling different needs of our valuable customers.



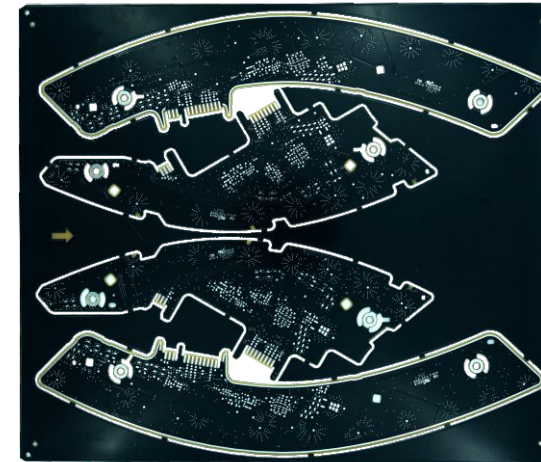
产品描述: 6层
材料要求: S1000-2M
完成厚度: 1.6mm
线宽线距: 3mils / 3mils
表面处理: 沉金 2U"
特殊管控: BGA + 金手指 30U"

Description: 6 Layers
Material: S1000-2M
Finished Thickness: 1.6mm
Line & Spacing: 3mils / 3 mils
Surface Finishing: ENIG 2U"
Special Request: BGA + Hard Gold 30U"

产品描述: 24层HDI 任意互联
材料要求: IT 180A
完成厚度: 1.8mm
线宽线距: 3mils / 3mils
表面处理: 沉金 2U"



Description: 24 Layers HDI Anylayer
Material: IT 180A
Finished Thickness: 1.8mm
Line & Spacing: 3mils / 3 mils
Surface Finishing: ENIG 2U"

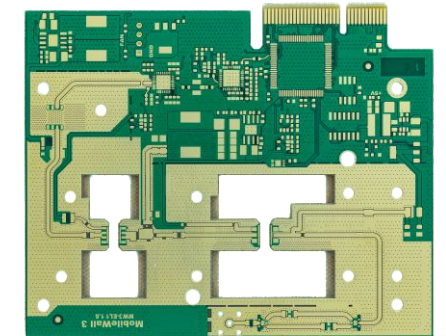


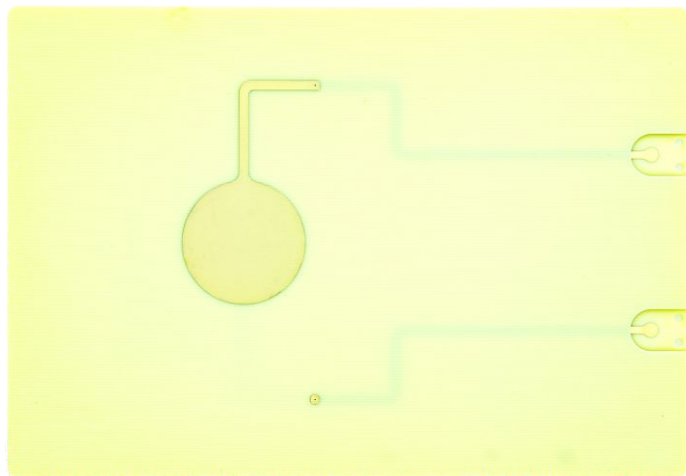
产品描述: 4层汽车灯板
材料要求: S1141
完成厚度: 1.2mm
线宽线距: 5mils / 5mils
表面处理: 沉锡
特殊管控: 哑黑色油墨

Description: 4 Layers Automotive Lighting
Material: S1141
Finished Thickness: 1.2mm
Line & Spacing: 5mils / 5 mils
Surface Finishing: Immersion Tin
Special Request: Matte Black Soldermask

产品描述: 6层高频板
材料要求: Rogers 4350B
完成厚度: 1.6mm
线宽线距: 4mils / 3mils
表面处理: 沉金 2U"
特殊管控: 金手指 + 控深钻

Description: 6 Layers High Frequency
Material: Rogers 4350B
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 3 mils
Surface Finishing: ENIG 2U"
Special Request: Golden Fingers + Depth Milling

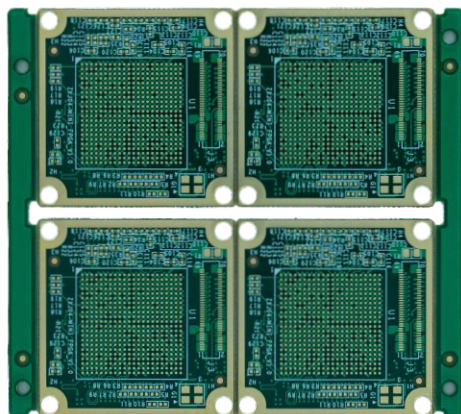




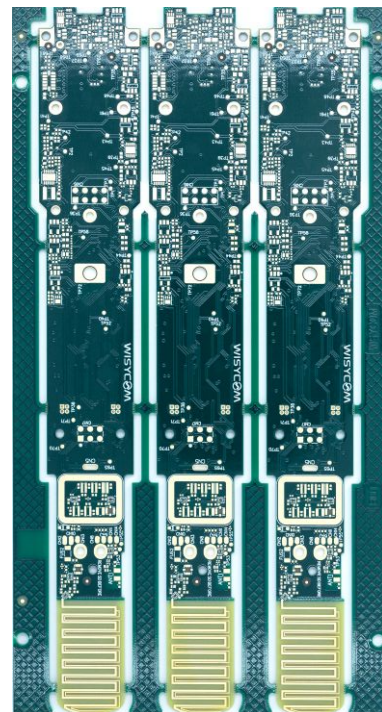
产品描述: 4层测试板
材料要求: S1000-2
完成厚度: 1.6mm
线宽线距: 10mils / 10mils
表面处理: 沉金 2U"
特殊管控: 控深钻

Description: 4 Layers Test Board
Material: S1000-2
Finished Thickness: 1.6mm
Line & Spacing: 10mils / 10 mils
Surface Finishing: ENIG 2U"
Special Request: Depth Milling Control

产品描述: 12层
材料要求: S1000-2M
完成厚度: 1.6mm
线宽线距: 3mils / 3mils
表面处理: 沉金 2U"
特殊管控: BGA 间距 0.3mm



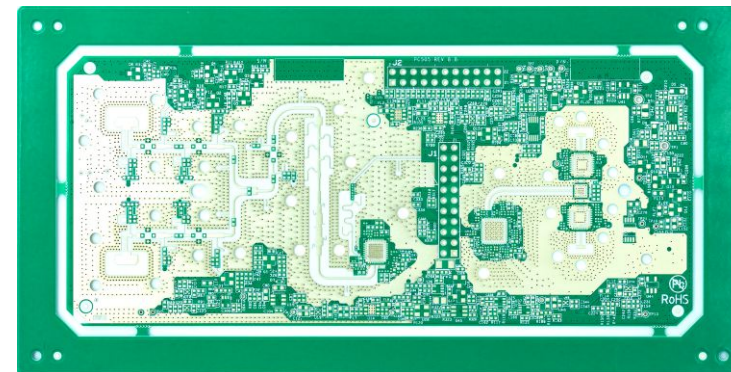
Description: 12 Layers
Material: S1000-2M
Finished Thickness: 1.6mm
Line & Spacing: 3mils / 3 mils
Surface Finishing: ENIG 2U"
Special Request: BGA Pitch 0.3mm



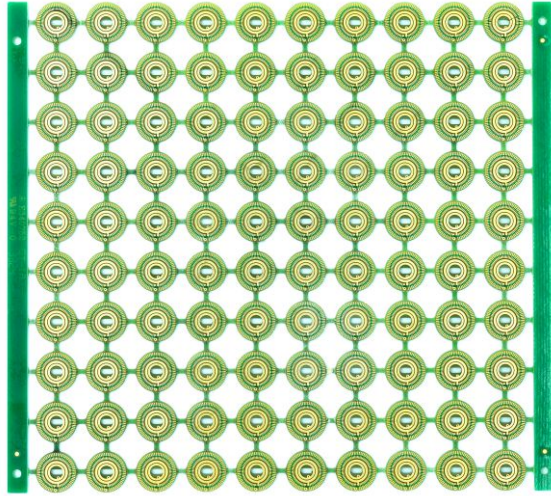
产品描述: 8层任意互联
材料要求: ISOLA 370HR
完成厚度: 1.6mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 8组阻抗

Description: 8 Layers HDI Anylayers
Material: ISOLA 370HR
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: ENIG 2U"
Special Request: 8 Sets of Impedance Control

产品描述: 6层高频板
材料要求: ROGERS 4350B
完成厚度: 1.6mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 阻抗要求 +/- 8%



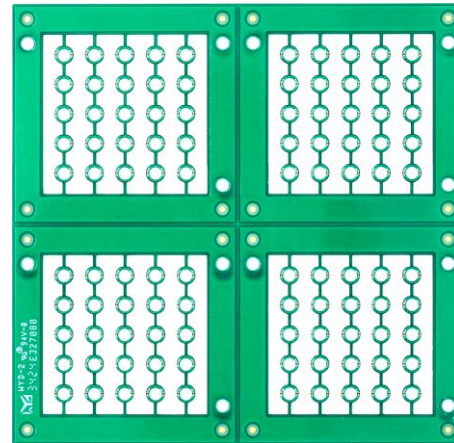
Description: 6 Layers High Frequency
Material: ROGERS 4350B
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: ENIG 2U"
Special Request: Impedance Control +/- 8%



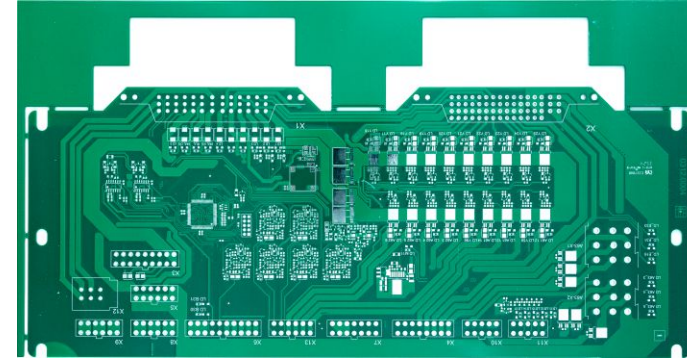
产品描述: 4层测试板
材料要求: S1000-2
完成厚度: 1.6mm
线宽线距: 10mils / 10mils
表面处理: 沉金 2U"
特殊管控: 外形公差 +/- 0.1mm

Description: 4 Layers Test Board
Material: S1000-2
Finished Thickness: 1.6mm
Line & Spacing: 10mils / 10 mils
Surface Finishing: ENIG 2U"
Special Request: Outline Tolerance +/- 0.1mm

产品描述: 2 层
材料要求: IT 180A
完成厚度: 0.8mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 外形公差 +/- 0.1mm



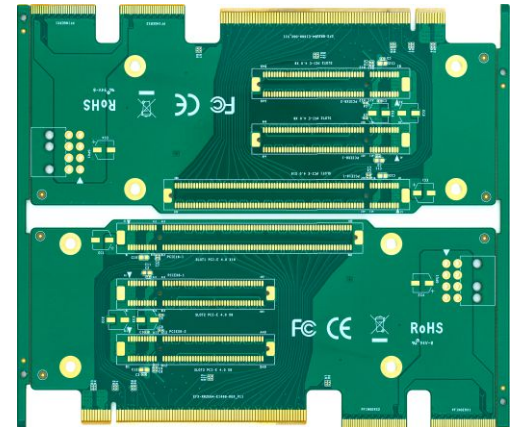
Description: 2 Layers
Material: IT 180A
Finished Thickness: 0.8mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: ENIG 2U"
Special Request: Outline Tolerance +/- 0.1mm



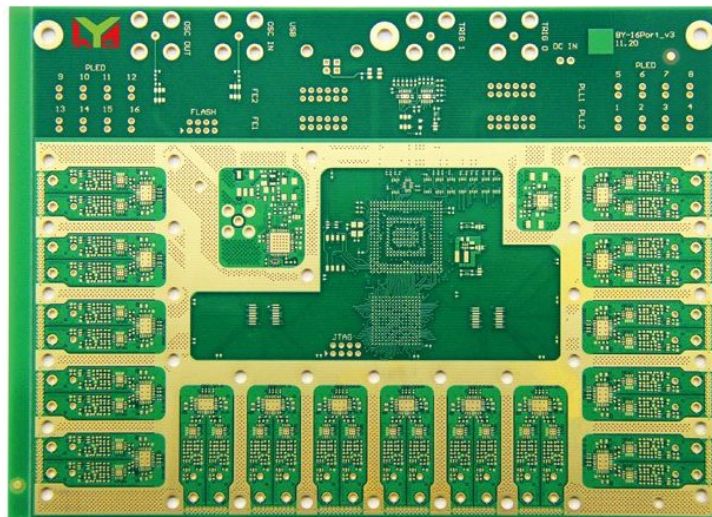
Description: 4 Layers
Material: S1170
Finished Thickness: 1.8mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: Immersion Tin
Special Request: 3 OZ Inner & Outer Cu

产品描述: 4 层
材料要求: S1170
完成厚度: 1.8mm
线宽线距: 4mils / 4mils
表面处理: 沉锡
特殊管控: 内外 3 OZ 完成铜厚

Description: 4 Layers
Material: S1000-2
Finished Thickness: 1.6mm
Line & Spacing: 5mils / 5 mils
Surface Finishing: ENIG 2U"
Special Request: Golden Finger + Bevel



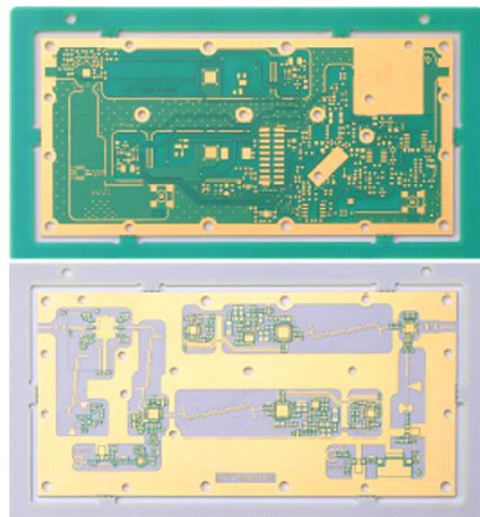
产品描述: 4 层
材料要求: S1000-2
完成厚度: 1.6mm
线宽线距: 5mils / 5mils
表面处理: 沉金 2U"
特殊管控: 金手指 + 斜边



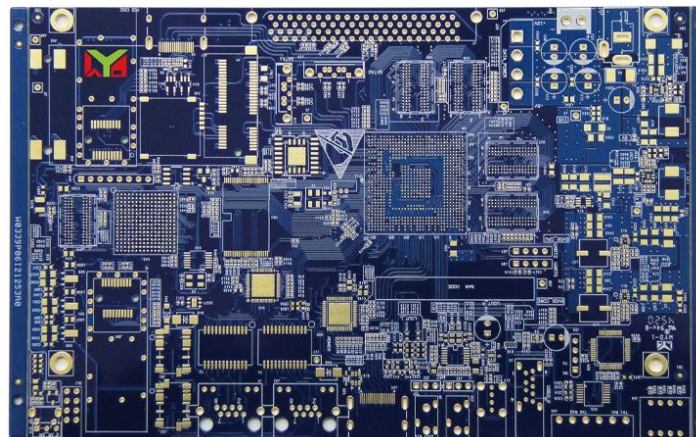
Description: 4 Layers Test Board
Material: S1000-2
Finished Thickness: 1.6mm
Line & Spacing: 10mils / 10 mils
Surface Finishing: ENIG 2U"
Special Request: Depth Milling Control

Description: 4 Layers 1 Step HDI
Material: ROGERS 4350B
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: ENIG 2U"
Special Request: Resin Plugging + Coppering Filling

产品描述: 4层 1 Step HDI
材料要求: ROGERS 4350B
完成厚度: 1.6mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 树脂塞孔 + 电镀填铜



产品描述: 12 层
材料要求: IT180A
完成厚度: 1.6mm
线宽线距: 4mils / 3.5mils
表面处理: 沉金 2U"
特殊管控: 阻抗要求 + 压接孔

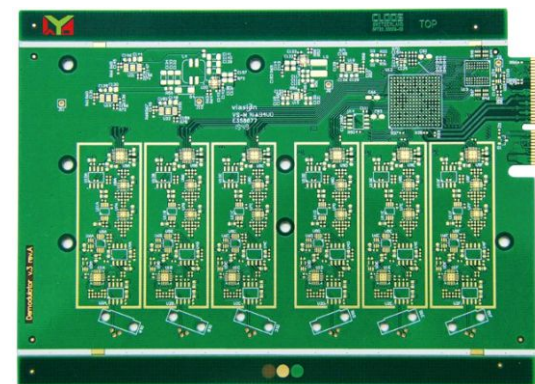


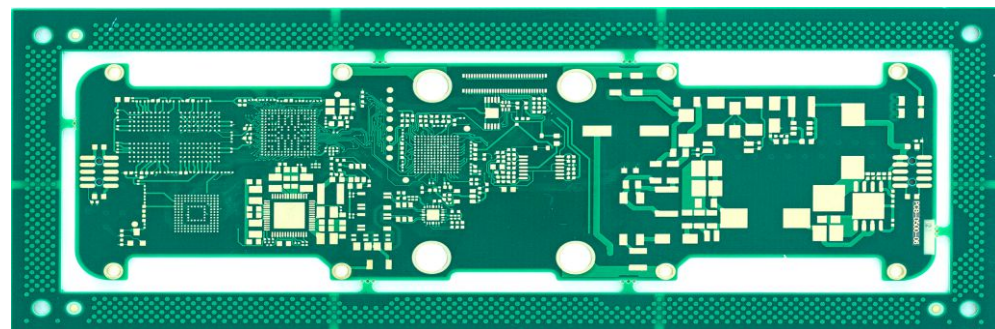
Description: 10 Layers 3 Step HDI
Material: IT180A
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 4 mils
Surface Finishing: ENIG 2U"
Special Request: Resin Plugging + Coppering Filling + Back Drill

Description: 6 Layers
Material: IT180A
Finished Thickness: 1.6mm
Line & Spacing: 5mils / 5 mils
Surface Finishing: Flash Gold
Special Request: IPC Class III + Golden Finger

产品描述: 10层 3 阶
材料要求: IT180A
完成厚度: 1.6mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 树脂塞孔 + 电镀填铜 + 背钻

产品描述: 6层
材料要求: IT180A
完成厚度: 1.6mm
线宽线距: 5mils / 5mils
表面处理: Flash Gold
特殊管控: IPC Class III + Golden Finger

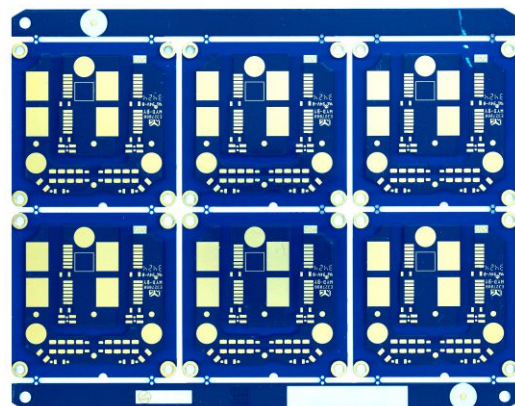




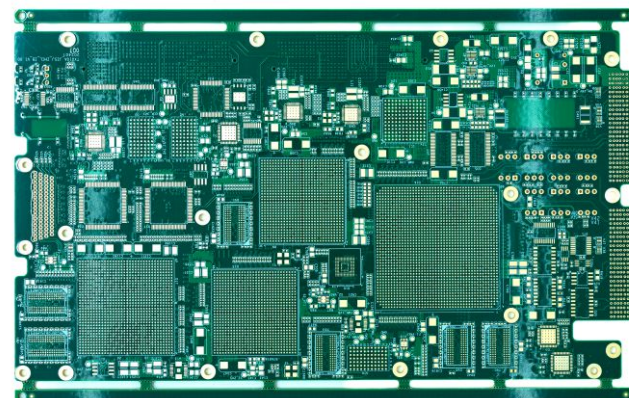
产品描述: 4 层
材料要求: IT180A
完成厚度: 1.6mm
线宽线距: 3mils / 3mils
表面处理: 沉金 2U"
特殊管控: BGA 0.3mm 间距

Description: 4 Layers
Material: IT180A
Finished Thickness: 1.6mm
Line & Spacing: 3mils / 3mils
Surface Finishing: ENIG 2U"
Special Request: BGA Pitch 0.3mm

产品描述: 单面铝基板
材料要求: 腾辉 4B 系列
完成厚度: 1.6mm
线宽线距: 10mils / 10mils
表面处理: 沉金 2U"
特殊管控: 3 OZ 铜厚 + 导热系数 4瓦



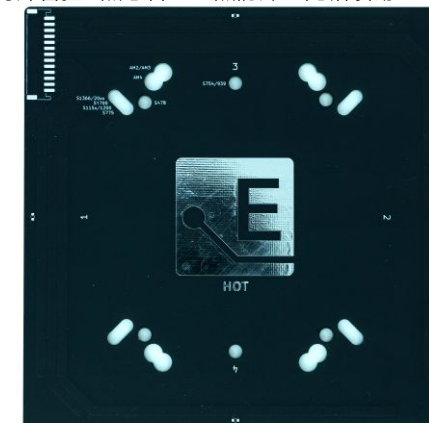
Description: Single Sided PCB
Material: Ventec 4B Series
Finished Thickness: 1.6mm
Line & Spacing: 10mils / 10mils
Surface Finishing: ENIG 2U"
Special Request: 3 OZ + Thermal Conductivity 4 kW



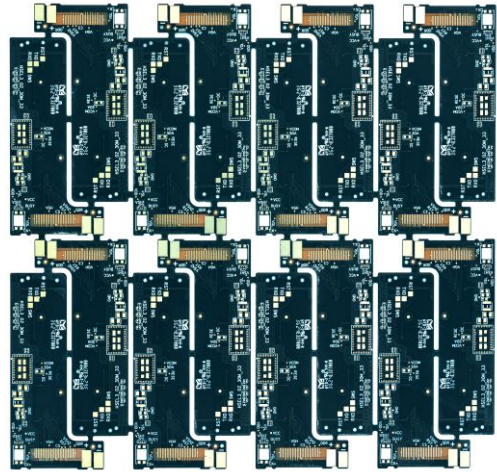
Description: 14 Layers
Material: IT180A
Finished Thickness: 1.6mm
Line & Spacing: 4mils / 4mils
Surface Finishing: ENIG 2U"
Special Request: Back Drill + BGAs + Impedance Control

产品描述: 14层
材料要求: IT180A
完成厚度: 1.6mm
线宽线距: 4mils / 4mils
表面处理: 沉金 2U"
特殊管控: 背钻 + BGAs + 阻抗要求

产品描述: 2层
材料要求: SI10US
完成厚度: 1.6mm
线宽线距: 5mils / 5mils
表面处理: HASL-LF
特殊管控: 黑芯料 + 哑黑防焊 + 无铅喷锡



Description: 2 Layers
Material: SI10US
Finished Thickness: 1.6mm
Line & Spacing: 5mils / 5mils
Surface Finishing: HASL-LF
Special Request: Black material + Matte Solder Mask + HASL-LF



Description: 6 Layers

Material: S1000-2

Finished Thickness: 0.8mm

Line & Spacing: 3mils / 4 mils

Surface Finishing: ENIG 2U"

Special Request: Depth Milling + Impedance Control +/-8%

产品描述: 6 层

材料要求: S1000-2

完成厚度: 0.8mm

线宽线距: 3mils / 4mils

表面处理: 沉金 2U"

特殊管控: 控深钻 + 阻抗+/-
8%

产品描述: 4 层

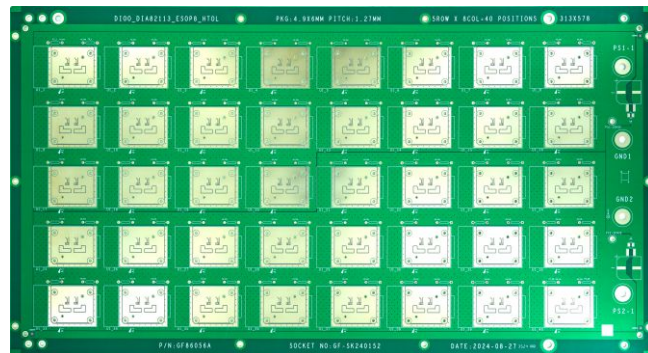
材料要求: IT158

完成厚度: 1.6mm

线宽线距: 5mils / 5mils

表面处理: 沉金 2U"

特殊管控: 阻抗要求



Description: 4 Layers

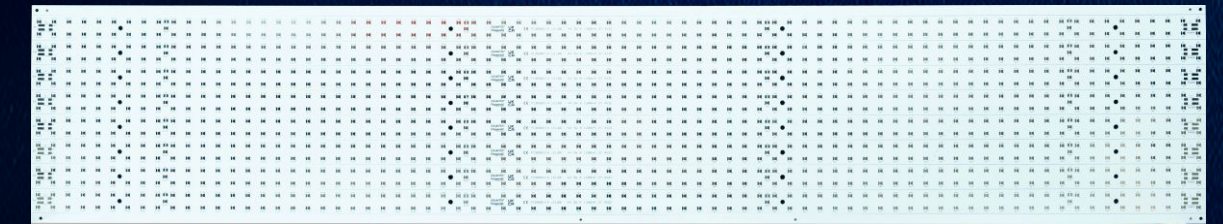
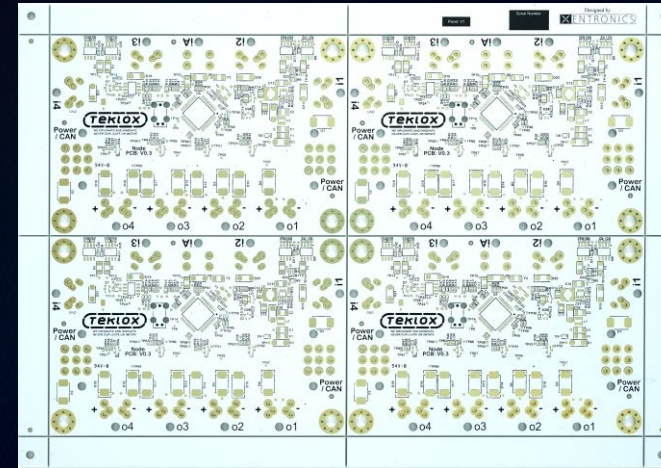
Material: IT158

Finished Thickness: 1.6mm

Line & Spacing: 5mils / 5 mils

Surface Finishing: ENIG 2U"

Special Request: Impedance Control



产品描述: 2层LED

材料要求: KB6160C

完成厚度: 1.2mm

线宽线距: 8mils / 8mils

表面处理: 无铅喷锡

特殊管控: 1200mm 长

Description: 2 Layers

Material: KB6160C

Finished Thickness: 1.2mm

Line & Spacing: 8mils / 8 mils

Surface Finishing: HASL-LF

Special Request: 1200mm Length



Drilling Dept
钻孔部



Flying Probe Tester
飞针测试机



Laser Drilling
镭射钻孔机



Legend Printing
字符打印机



Etching Line
蚀刻线



Pressing Line
压合机



Pattern Plating
图形电镀



AOI



LDI Exposure Machine
LDI 曝光机



V-Cut Machine
V-Cut 机



Hole Checking Machine
验孔机

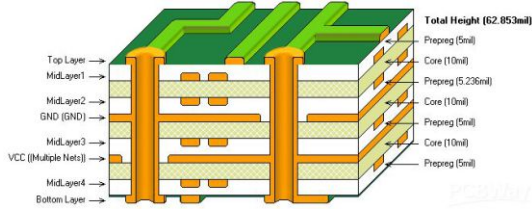


X-Ray Inner Checker
X-Ray 测试仪



Surface Copper Tester
铜厚测量仪

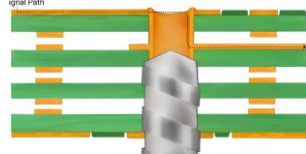
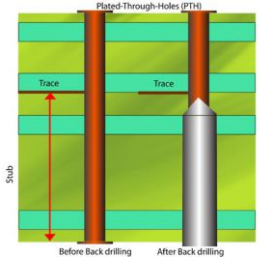
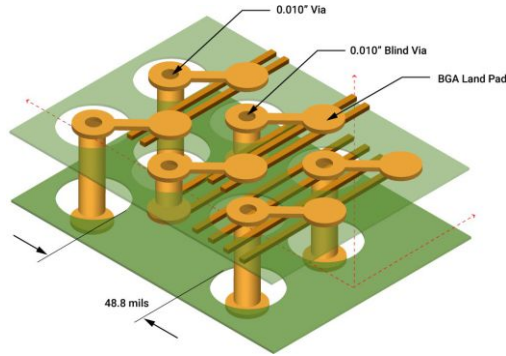
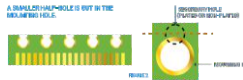
	高频板	
	通用参数	极限能力
层数	8层 (FR-4+罗杰斯混压)	12层 (罗杰斯)
最大交货尺寸	300mm*450mm	400mm*500mm
Tg值	TG280	
板厚	1.6mm	2.4mm
外层铜厚(完成)	10Z	20Z
内层铜厚(完成)	10Z	20Z
纵横比	12:01	15:01
表面处理	抗氧化处理 / 无铅喷锡 / 沉金 / 沉镍钯金 / 电金 / 沉锡 / 沉银	
最小完成孔径	0.2mm	0.15
最小线宽线距(外层)	3 mils	2 mils
最小线宽线距(内层)	3 mils	2 mils
最小防焊绿油桥	5 mils	3 mils
半孔	20 mils	8 mils



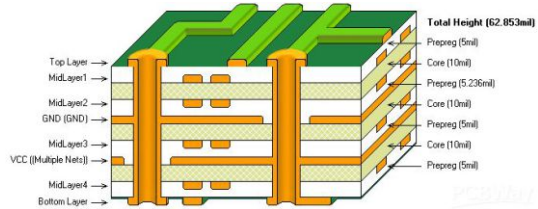
	FR-4硬板	
	通用参数	极限能力
层数	24层	40层
最大交货尺寸	950mm*600mm	1200mm*600mm
Tg值	TG135,TG150,TG170,TG180	
板厚	5.0MM	6.0MM
外层铜厚(完成)	80Z	100Z
内层铜厚(完成)	60Z	80Z
纵横比	1:12	1:15
表面处理	抗氧化处理 / 无铅喷锡 / 沉金 / 沉镍钯金 / 电金 / 沉锡 / 沉银	
最小完成孔径	0.15mm	0.1mm
最小线宽线距(外层)	3 mils	2 mils
最小线宽线距(内层)	3 mils	2 mils
最小 BGA 间距	12 mils	8 mils
阻抗能力	+/-10%	+/-7%
最小防焊绿油桥	5 mils	3 mils
半孔	20 mils	8 mils
背钻	3次	6次

	HDI	
	通用参数	极限能力
层数	24层	32层
HDI	2阶 - 3阶	5阶
最大交货尺寸	300mm *450mm	400mm *500mm
材料	FR-4 TG 170	Roger 4350, 371HR
外层铜厚(完成)	10Z	20Z
内层铜厚(完成)	23	20Z
纵横比 (PTH)	34	2:15
纵横比 (槽射孔)	2:01	0.8:2
表面处理	抗氧化处理 / 无铅喷锡 / 沉金 / 沉镍钯金 / 电金 / 沉锡 / 沉银	
最大槽射孔径	0.15mm	0.2mm
最小线宽线距(外层)	3 mils	2 mils
最小线宽线距(内层)	3 mils	2 mils
最小防焊绿油桥	5 mils	3 mils
半孔	20 mils	8 mils

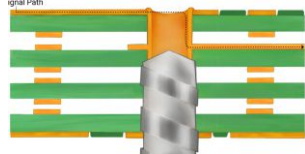
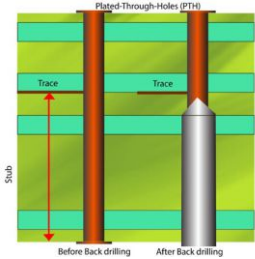
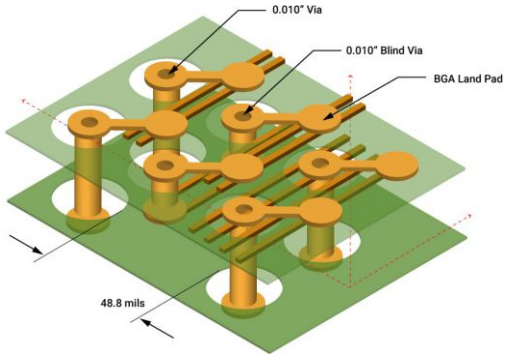
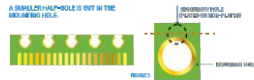
	铝基板	
	通用参数	极限能力
层数	4层	6层
最大交货尺寸	400mm*500mm	1000mm*500mm
导热系数	4瓦	7瓦
最大板厚	5.00 mm	6.00mm
外层铜厚(完成)	10Z	00Z
内层铜厚(完成)	30Z	20Z
纵横比	10:01	12:01
表面处理	抗氧化 / 沉金	
最小孔径(完成)	1.00mm	0.90mm



	High Frequency PCB	
	Standard	Advance
Layer Count	8 Layers (FR-4 + Rogers)	12 Layers (Rogers)
Max PCB Delivery Size	300*450	400*500
Tg	280	
Board Thickness	1.6mm	2.4mm
Outer Based Cu	10Z	20Z
Inner Based Cu	10Z	20Z
Aspect Ratio	12:01	15:01
Surface Treatment	HASL-LF,EING, ENPIG, OSP, GOLD FINGER,IMMERSION TIN,IMMERSION SILVER	
Drill Hole Size	0.2mm	0.15
Min Line / Spacing Outer	3 mils	2 mils
MIN Line / Spacing Inner	3 mils	2 mils
Min Solder Mask Bridge	5 mils	3 mils
Half Holes	20 mils	8 mils

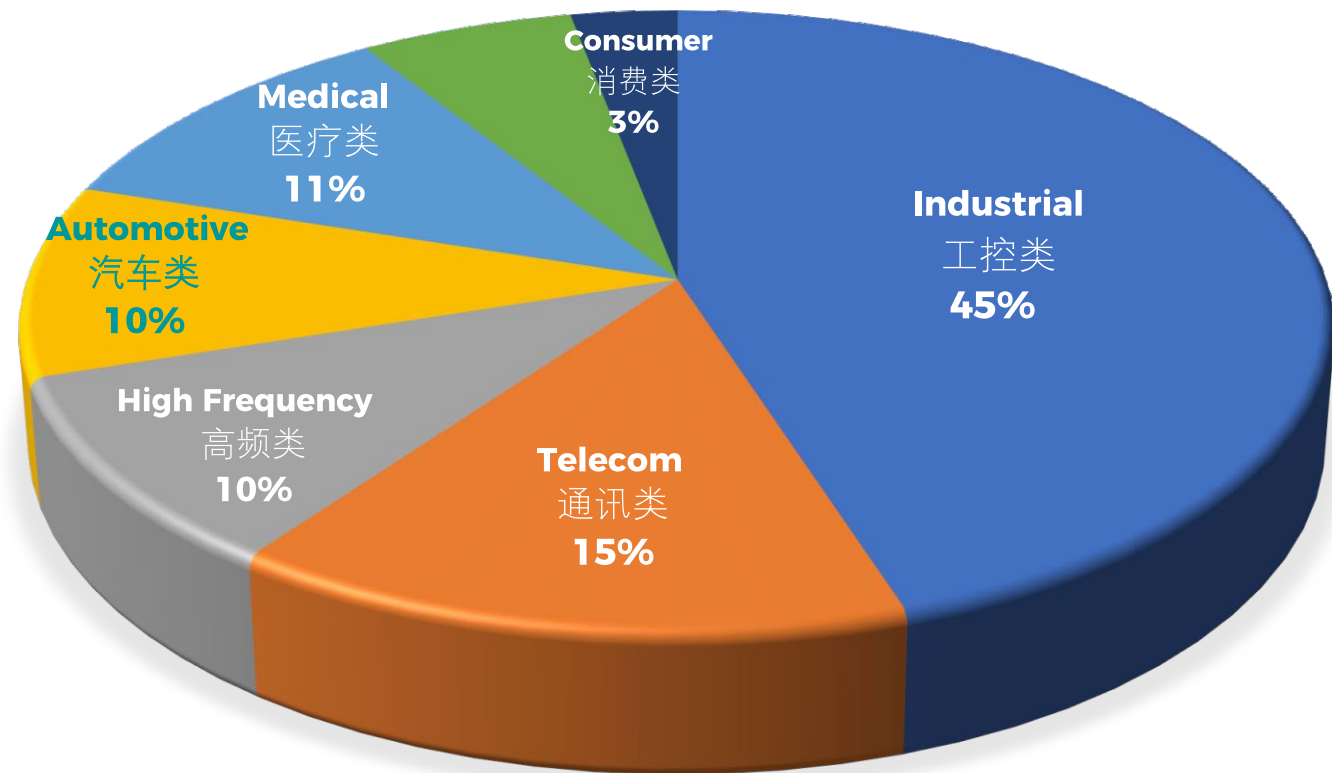


	Standard RIGID PCB	
	Standard	Advance
Layer Count	24 Layers	40 Layers
Max PCB Delivery Size	950mm*600mm	1200mm*600mm
Tg	TG135,TG150,TG170,TG180	
Board Thickness	5.0MM	6.0MM
Outer Based Cu	80Z	100Z
Inner Based Cu	60Z	80Z
Aspect Ratio	1:12	1:15
Surface Treatment	HASL-LF,EING, ENPIG, OSP, GOLD FINGER,IMMERSION TIN,IMMERSION SILVER	
Hole Size	0.15 mm	0.1 mm
Min Line / Spacing Outer	3 mils	2 mils
MIN Line / Spacing Inner	3 mils	2 mils
Min BGA Pitch	12 mils	8 mils
Impedance	10%	7%
Min Solder Mask Bridge	5 mils	3 mils
Half Holes (PTH)	20 mils	8 mils
Back Drill	3 Times	6 Times



	HDI	
	Standard	Advance
Layer Count	24 Layers	32 Layers
HDI	1 Step - 3 Steps	4 Steps & Anylayer
Max PCB Delivery Size	300*450	400*500
Raw Material	FR-4 TG 170	Roger 4350, 370HR
Outer Based Cu	10Z	20Z
Inner Based Cu	1	20Z
Apect Ratio (PTH)	12	1:15
Apect Ratio (Laser)	1:01	0.8:1
Surface Treatment	HASL-LF, ENIG,OSP,GOLD FINGER,IMMERSION TIN,IMMERSION SILVER	
Laser Hole Size	0.15mm	0.2mm
Min Line / Spacing Outer	3 mils	2 mils
MIN Line / Spacing Inner	3 mils	2 mils
Min Solder Mask Bridge	5 mils	3 mils
Half Holes	20 mils	8 mils

	IMS Project (Alu Based PCB)	
	Standard	Advance
Layer Count	4	6
Max PCB Delivery Size	400mm*500mm	1000mm*500mm
Thermal Conductivity	4kW	7Kw
Board Thickness	5mm	6mm
Outer Based Cu	30Z	40Z
Inner Based Cu	10Z	20Z
Aspect Ratio	10:01	12:01
Surface Treatment	OSP / ENIG	
Min Hole Sizes	1.0mm	0.8mm



Consumer
消费类 3%



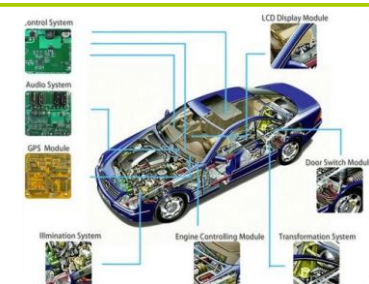
Industrial
工控类 45%



Telecom
通讯类 15%



High Frequency
高频类 10%



Automotive
汽车类 10%



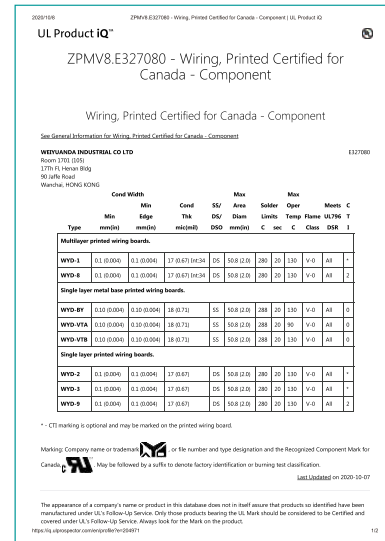
Medical
医疗类 11%



ISO 9001: 2015



ISO 14001: 2015



Canada UL E327080



IATF 16949: 2015



US UL E327080

